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Atty Docket #:
ONS00031



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1. Name of conveying part(ies):
Yoshinori Saito
8-201

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Name: Semiconductor Components Industries, LLC
Internal Address: Patent Administration Dept. - A230
Street Address: 5005 East McDowell Road
City: Phoenix State: AZ ZIP: 85008

3. Nature of conveyance:
 Assignment Merger
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Execution date of conveyance: April 4, 2000

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s): 09/636,646
If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s):

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5. Name and address of party to whom correspondence concerning document should be mailed:
Name: Semiconductor Components Industries, LLC
Internal Address: Patent Administration Dept - MD A230
Street Address: P.O. Box 62890
City, State, Zip: Phoenix, AZ 85082-2890

6. Total number of applications and patents involved: 1
7. Total fee (37 C.F.R. 3.41)..... \$ 40.00
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ASSIGNMENT AND AGREEMENT

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I hereby also sell, assign, and transfer unto SCI, the entire right, title, and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the inventions and the applications for Letters Patent in foreign countries, and I further authorize SCI to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

I hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation, or reissue, to SCI, for the sole use and behalf of SCI, its successors, assigns, and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and I hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to SCI.

I agree that, when requested, I will, without charge to SCI, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in SCI, its successors, assigns, and legal representatives or nominees.

I covenant with SCI, its successors, assigns, and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

Yoshinori Saito
Yoshinori Saito

Date: April 4, 2000

Witnessed by: Yoshio Enosawa
Signature

YOSHIO ENOSAWA
Printed Name

Address correspondence concerning this document to: Semiconductor Components Industries, LLC, Patent Administration Dept - MD A230, P.O. Box 62890, Phoenix, AZ 85082-2890.